



flowPACK E1 SiC

1200 V / 30 mΩ

Topology features

- 3ph Inverter
- Low and high side Kelvin Emitter for improved switching performance
- MOSFET
- Open Emitter configuration
- Temperature sensor

Component features

- High Blocking Voltage with low drain source on state resistance
- High speed SiC-MOSFET technology
- Resistant to Latch-up

Housing features

- Base isolation: Al₂O₃
- Convex shaped substrate for superior thermal contact
- Compact housing
- CTI600 housing material
- Thermo-mechanical push-and-pull force relief
- Press-fit pin
- Reliable cold welding connection

Target applications

- Charging Stations
- Elevator Drives
- Industrial Drives
- Servo Drives

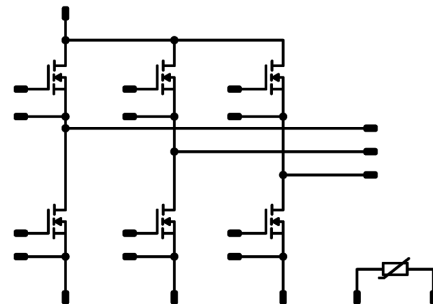
Types

- 10-EZ126PB030MS-LS18F78T

flow E1 12 mm housing



Schematic





Vincotech

10-EZ126PB030MS-LS18F78T
datasheet

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | Unit |
|------------------------------|------------|---------------------------------------|----------|------|
| Inverter Switch | | | | |
| Drain-source voltage | V_{DS} | | 1200 | V |
| Drain current (DC current) | I_D | $T_j = T_{jmax}$ $T_s = 80\text{ °C}$ | 41 | A |
| Peak drain current | I_{DM} | t_p limited by T_{jmax} | 160 | A |
| Total power dissipation | P_{tot} | $T_j = T_{jmax}$ $T_s = 80\text{ °C}$ | 78 | W |
| Gate-source voltage | V_{GS} | | -5 / 18 | V |
| | | dynamic | -10 / 22 | |
| Maximum Junction Temperature | T_{jmax} | | 175 | °C |

Module Properties

Thermal Properties

| | | | | |
|---|-----------|--|----------------------------|----|
| Storage temperature | T_{sg} | | -40...+125 | °C |
| Operation temperature under switching condition | T_{jop} | | -40...+($T_{jmax} - 25$) | °C |

Isolation Properties

| | | | | |
|----------------------------|------------|-------------------------------------|-------|----|
| Isolation voltage | V_{isol} | DC Test Voltage* $t_p = 2\text{ s}$ | 6000 | V |
| Creepage distance | | | >12,7 | mm |
| Clearance | | | 8,74 | mm |
| Comparative Tracking Index | CTI | | ≥ 600 | |

*100 % tested in production



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Characteristic Values

| Parameter | Symbol | Conditions | | | | | Values | | | Unit |
|-----------|--------|------------------------------|---|-------------------------------------|------------|-----|--------|-----|--|------|
| | | V_{GE} [V] V_{GS} [V] | V_{CE} [V] V_{DS} [V] V_F [V] | I_C [A] I_D [A] I_F [A] | T_j [°C] | Min | Typ | Max | | |

Inverter Switch

Static

| | | | | | | | | | | |
|---|--------------|---------------|-------|------|-------|-----------|-----|----------|------|----|
| Drain-source on-state resistance ⁽¹⁾ | $r_{DS(on)}$ | | 18 | | 40 | 25 175 | | 30 49 | | mΩ |
| | | | 15 | | | 25 175 | | 40 53 | | |
| Gate-source threshold voltage | $V_{GS(th)}$ | | | | 0,004 | 25 | 1,7 | 2,25 | 2,75 | V |
| Gate to Source Leakage Current | I_{GSS} | | 22 | 0 | | 25 | | | 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | | 0 | 1200 | | 25 | | | 10 | μA |
| Internal gate resistance | r_g | | | | | | | 2 | | Ω |
| Gate charge | Q_g | | -5/18 | 800 | 40 | 25 | | 108 | | nC |
| Short-circuit input capacitance | C_{iss} | $f = 500$ kHz | | | | | | 2600 | | pF |
| Short-circuit output capacitance | C_{oss} | | 0 | 800 | 0 | 25 | | 135 | | |
| Reverse transfer capacitance | C_{rss} | | | | | | | 6 | | |
| Diode forward voltage | V_{SD} | | 0 | | 40 | 25 | | 4,1 | | V |

Thermal

| | | | | | | | | | | |
|--|---------------|---------------------------------------|--|--|--|--|--|------|--|-----|
| Thermal resistance junction to sink ⁽²⁾ | $R_{th(j-s)}$ | $\lambda_{paste} = 3,4$ W/mK (PSX) | | | | | | 1,21 | | K/W |
|--|---------------|---------------------------------------|--|--|--|--|--|------|--|-----|



Vincotech

10-EZ126PB030MS-LS18F78T
datasheet

Characteristic Values

| Parameter | Symbol | Conditions | | | | | Values | | | Unit | | | | |
|---------------------------------------|----------------------|--|---|-------------------------------------|------------|--|--------|----------|--|------------|--|-------|--|-----|
| | | V_{GE} [V] V_{GS} [V] | V_{CE} [V] V_{DS} [V] V_F [V] | I_C [A] I_D [A] I_F [A] | T_j [°C] | Min | Typ | Max | | | | | | |
| Dynamic | | | | | | | | | | | | | | |
| Turn-on delay time | $t_{d(on)}$ | $R_{gon} = 4 \Omega$ $R_{goff} = 4 \Omega$ | -5/18 | 600 | 32 | 25 | | 18,89 | | ns | | | | |
| | | | | | | 125 | | 17,14 | | | | | | |
| | | | | | | 150 | | 16,96 | | | | | | |
| Rise time | t_r | | | | | 25 | | 7,53 | | | | | | |
| | | | | | | 125 | | 7,11 | | ns | | | | |
| | | | | | | 150 | | 6,86 | | | | | | |
| Turn-off delay time | $t_{d(off)}$ | | | | | 25 | | 41,02 | | | | | | |
| | | | | | | 125 | | 46,87 | | ns | | | | |
| | | | | | | 150 | | 48,45 | | | | | | |
| Fall time | t_f | | | | | 25 | | 11,13 | | | | | | |
| | | | | | | 125 | | 12,77 | | ns | | | | |
| | | | | | | 150 | | 12,02 | | | | | | |
| Turn-on energy (per pulse) | E_{on} | | | | | $Q_{rFWD}=0,285 \mu C$ $Q_{rFWD}=0,661 \mu C$ $Q_{rFWD}=0,782 \mu C$ | | | | 25 | | 0,274 | | mWs |
| | | | | | | | | | | 125 | | 0,317 | | |
| | | | | | | | | | | 150 | | 0,327 | | |
| Turn-off energy (per pulse) | E_{off} | | | | | 25 | | 0,088 | | mWs | | | | |
| | | | | | | 125 | | 0,094 | | | | | | |
| | | | | | | 150 | | 0,097 | | | | | | |
| Peak recovery current | I_{RRM} | | | | | 25 | | 36,92 | | A | | | | |
| | | | | | | 125 | | 59,77 | | | | | | |
| | | | | | | 150 | | 67,84 | | | | | | |
| Reverse recovery time | t_{rr} | | | | | 25 | | 13,16 | | ns | | | | |
| | | | | | | 125 | | 17,42 | | | | | | |
| | | | | | | 150 | | 18,06 | | | | | | |
| Recovered charge | Q_r | $di/dt=4808 A/\mu s$ $di/dt=5493 A/\mu s$ $di/dt=5860 A/\mu s$ | | | | 25 | | 0,285 | | μC | | | | |
| | | | | | | 125 | | 0,661 | | | | | | |
| | | | | | | 150 | | 0,782 | | | | | | |
| Reverse recovered energy | E_{rec} | | | | | 25 | | 0,091 | | mWs | | | | |
| | | | | | | 125 | | 0,282 | | | | | | |
| | | | | | | 150 | | 0,347 | | | | | | |
| Peak rate of fall of recovery current | $(di_{rr}/dt)_{max}$ | | | | | 25 | | 8580,22 | | A/ μs | | | | |
| | | | | | | 125 | | 15306,96 | | | | | | |
| | | | | | | 150 | | 19970,52 | | | | | | |



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Characteristic Values

| Parameter | Symbol | Conditions | | | | | Values | | | Unit |
|-----------|--------|--------------|--------------|--------------|--------------|------------|--------|-----|-----|------|
| | | V_{GS} [V] | V_{GE} [V] | V_{DS} [V] | V_{CE} [V] | T_j [°C] | Min | Typ | Max | |

Thermistor

Static

| | | | | | | | | | | |
|--------------------------------|---------------|------------------------|--|--|--|-----|-----|------|-----|------|
| Rated resistance | R | | | | | 25 | | 5 | | kΩ |
| Deviation of R100 | $A_{R/R}$ | $R_{100} = 499 \Omega$ | | | | 100 | 3,2 | | 3,3 | % |
| Power dissipation | P | | | | | 25 | | 130 | | mW |
| Power dissipation constant | d | | | | | 25 | | 1,3 | | mW/K |
| B-value | $B_{(25/50)}$ | Tol. $\pm 1 \%$ | | | | | | 3380 | | K |
| Vincotech Thermistor Reference | | | | | | | | | V | |

⁽¹⁾ Value at chip level

⁽²⁾ Only valid with pre-applied Vincotech thermal interface material.

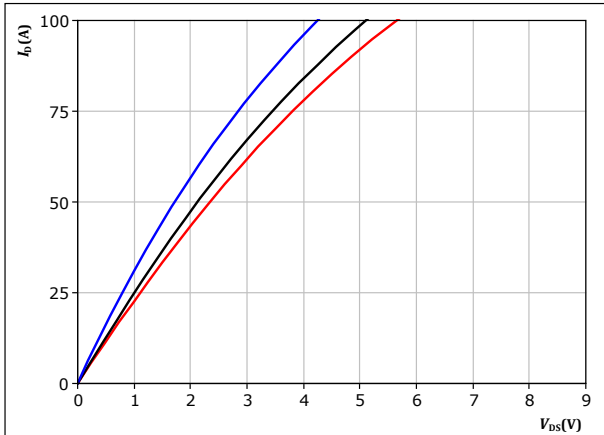


Inverter Switch Characteristics

figure 1. MOSFET

Typical output characteristics including $R_{DS(on)}$ and $R_{DS(off)}$

$I_D = f(V_{DS})$



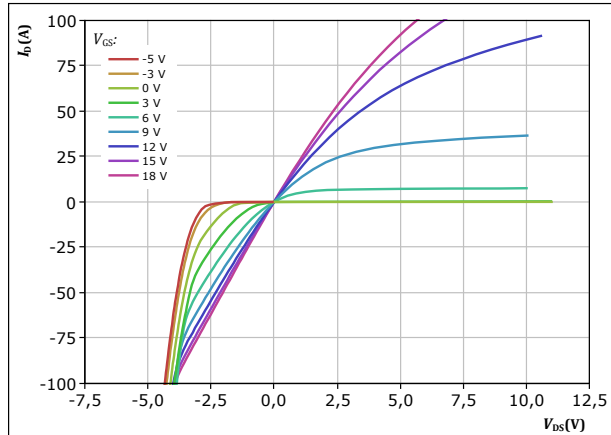
$t_p = 250 \mu s$
 $V_{GS} = 18 V$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 2. MOSFET

Typical output characteristics including $R_{DS(on)}$ and $R_{DS(off)}$

$I_D = f(V_{DS})$

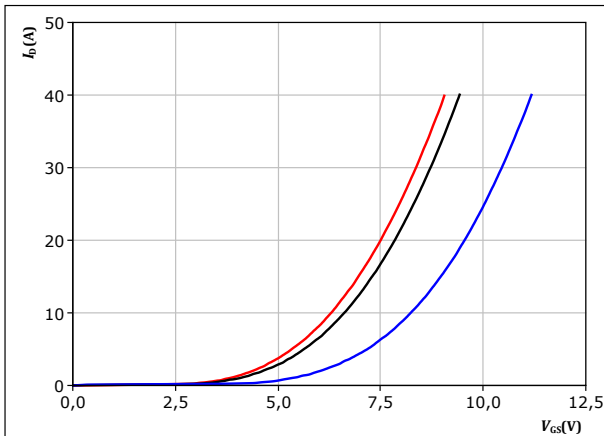


$t_p = 250 \mu s$
 $T_j = 150 \text{ °C}$
 V_{GS} from -5 V to 18 V in steps of 3 V

figure 3. MOSFET

Typical transfer characteristics

$I_D = f(V_{GS})$



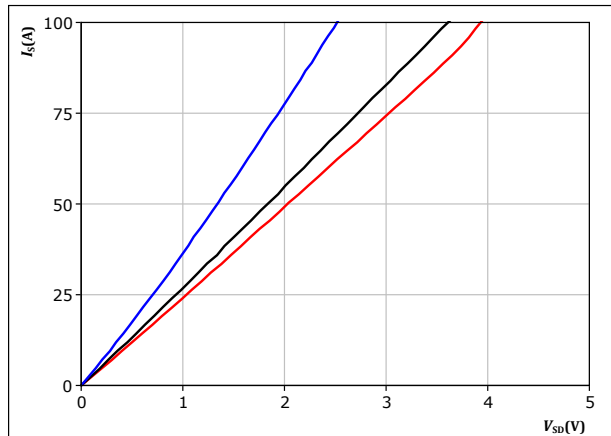
$t_p = 250 \mu s$
 $V_{DS} = 10 V$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 4. MOSFET

Typical reverse drain current characteristics including $R_{DS(on)}$ and $R_{DS(off)}$

$I_{SD} = f(V_{SD})$



$t_p = 250 \mu s$
 $V_{GS} = 18 V$

T_j : — 25 °C
— 125 °C
— 150 °C

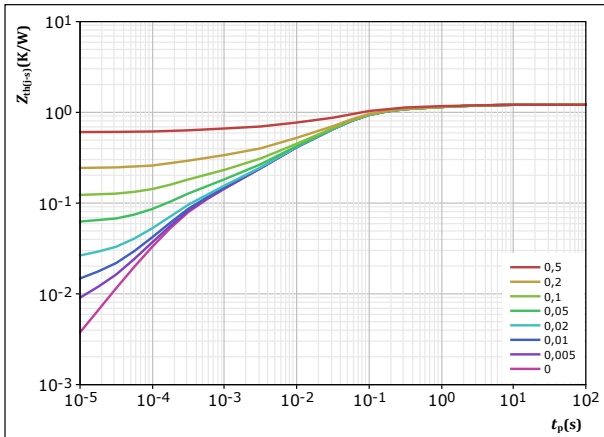


Inverter Switch Characteristics

figure 5. MOSFET

Transient thermal impedance as a function of pulse width

$$Z_{th(j-c)} = f(t_p)$$



$$D = t_p / T$$

$$R_{th(j-c)} = 1,212 \text{ K/W}$$

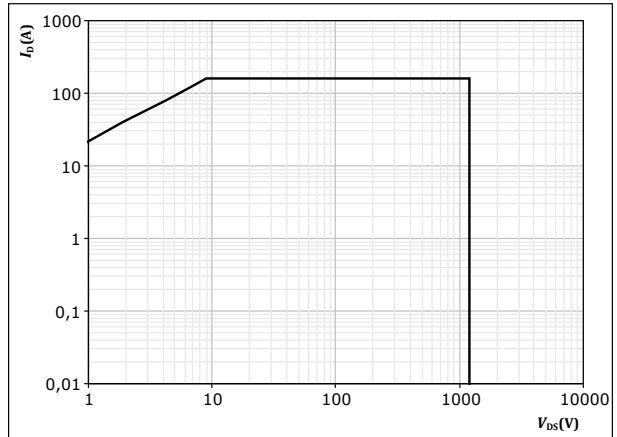
MOSFET thermal model values

| R (K/W) | τ (s) |
|----------|------------|
| 1,11E-01 | 1,92E+00 |
| 2,36E-01 | 1,61E-01 |
| 5,79E-01 | 3,90E-02 |
| 1,97E-01 | 4,33E-03 |
| 9,01E-02 | 2,81E-04 |

figure 6. MOSFET

Safe operating area

$$I_D = f(V_{DS})$$



D = single pulse

$$T_s = 80 \text{ } ^\circ\text{C}$$

$$V_{GS} = 18 \text{ V}$$

$$T_1 = T_{jmax}$$

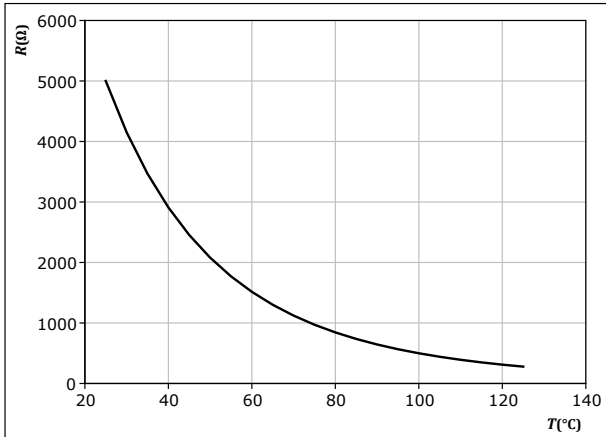


Thermistor Characteristics

figure 7. Thermistor

Typical NTC characteristic as function of temperature

$$R_T = f(T)$$

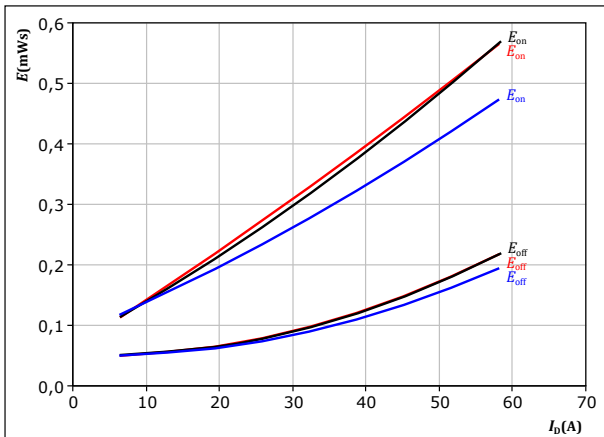




Inverter Switching Characteristics

figure 8. MOSFET

Typical switching energy losses as a function of drain current
 $E = f(I_D)$

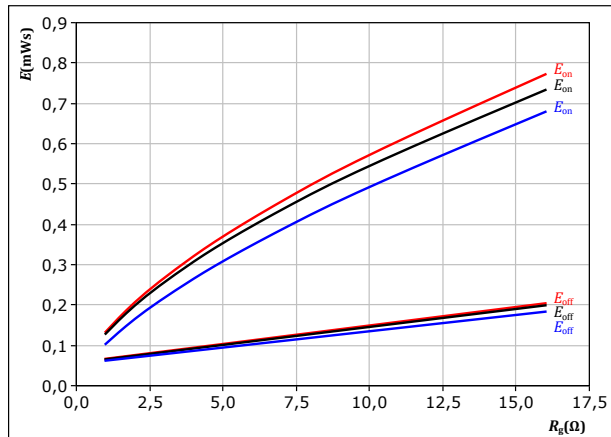


With an inductive load at

| | | | | |
|--------------|-------|----------|--------|----------|
| $V_{DS} =$ | 600 | V | $T_j:$ | — 25 °C |
| $V_{GS} =$ | -5/18 | V | | — 125 °C |
| $R_{gon} =$ | 4 | Ω | | — 150 °C |
| $R_{goff} =$ | 4 | Ω | | |

figure 9. MOSFET

Typical switching energy losses as a function of MOSFET turn on gate resistor
 $E = f(R_g)$

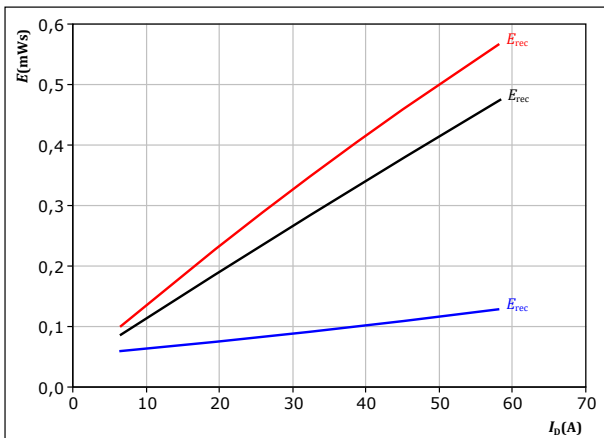


With an inductive load at

| | | | | |
|------------|-------|---|--------|----------|
| $V_{DS} =$ | 600 | V | $T_j:$ | — 25 °C |
| $V_{GS} =$ | -5/18 | V | | — 125 °C |
| $I_D =$ | 32 | A | | — 150 °C |

figure 10. MOSFET

Typical reverse recovered energy loss as a function of drain current
 $E_{rec} = f(I_D)$

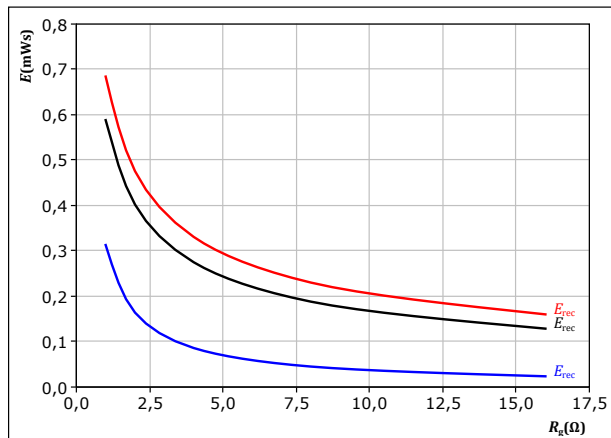


With an inductive load at

| | | | | |
|-------------|-------|----------|--------|----------|
| $V_{DS} =$ | 600 | V | $T_j:$ | — 25 °C |
| $V_{GS} =$ | -5/18 | V | | — 125 °C |
| $R_{gon} =$ | 4 | Ω | | — 150 °C |

figure 11. MOSFET

Typical reverse recovered energy loss as a function of MOSFET turn on gate resistor
 $E_{rec} = f(R_g)$



With an inductive load at

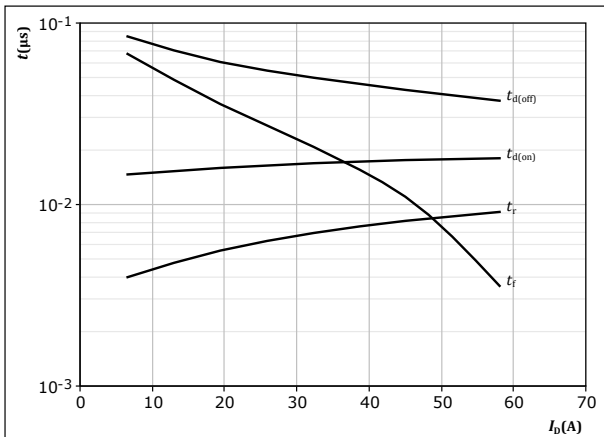
| | | | | |
|------------|-------|---|--------|----------|
| $V_{DS} =$ | 600 | V | $T_j:$ | — 25 °C |
| $V_{GS} =$ | -5/18 | V | | — 125 °C |
| $I_D =$ | 32 | A | | — 150 °C |



Inverter Switching Characteristics

figure 12. MOSFET

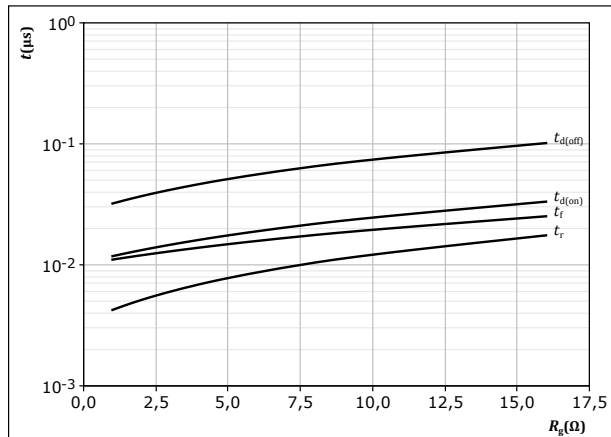
Typical switching times as a function of drain current
 $t = f(I_D)$



With an inductive load at
 $T_j = 150 \text{ } ^\circ\text{C}$
 $V_{DS} = 600 \text{ V}$
 $V_{GS} = -5/18 \text{ V}$
 $R_{gon} = 4 \text{ } \Omega$
 $R_{goff} = 4 \text{ } \Omega$

figure 13. MOSFET

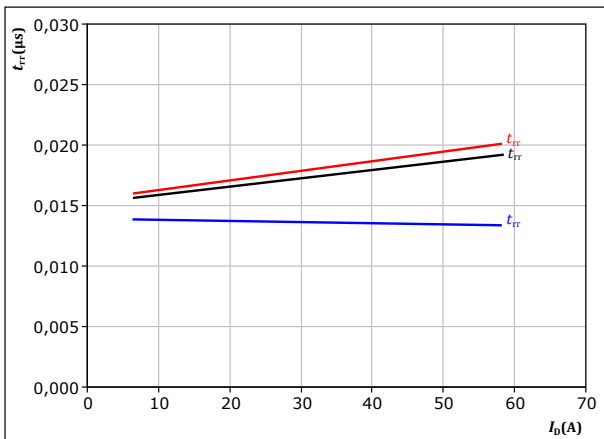
Typical switching times as a function of MOSFET turn on gate resistor
 $t = f(R_g)$



With an inductive load at
 $T_j = 150 \text{ } ^\circ\text{C}$
 $V_{DS} = 600 \text{ V}$
 $V_{GS} = -5/18 \text{ V}$
 $I_D = 32 \text{ A}$

figure 14. MOSFET

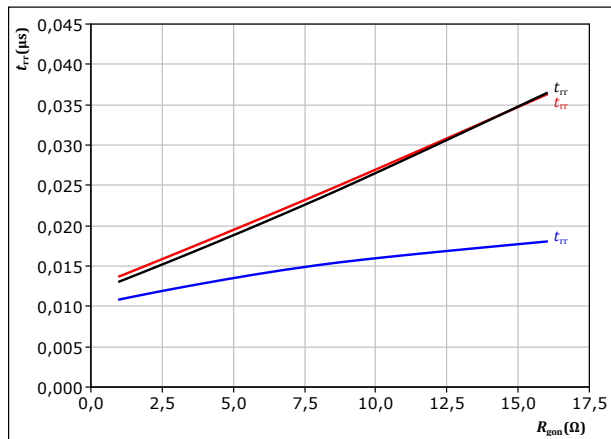
Typical reverse recovery time as a function of drain current
 $t_{rr} = f(I_D)$



At $V_{DS} = 600 \text{ V}$
 $V_{GS} = -5/18 \text{ V}$
 $R_{gon} = 4 \text{ } \Omega$
 $T_j: \text{ } \text{---} 25 \text{ } ^\circ\text{C}$
 $\text{---} 125 \text{ } ^\circ\text{C}$
 $\text{---} 150 \text{ } ^\circ\text{C}$

figure 15. MOSFET

Typical reverse recovery time as a function of MOSFET turn on gate resistor
 $t_{rr} = f(R_{gon})$



At $V_{DS} = 600 \text{ V}$
 $V_{GS} = -5/18 \text{ V}$
 $I_D = 32 \text{ A}$
 $T_j: \text{ } \text{---} 25 \text{ } ^\circ\text{C}$
 $\text{---} 125 \text{ } ^\circ\text{C}$
 $\text{---} 150 \text{ } ^\circ\text{C}$

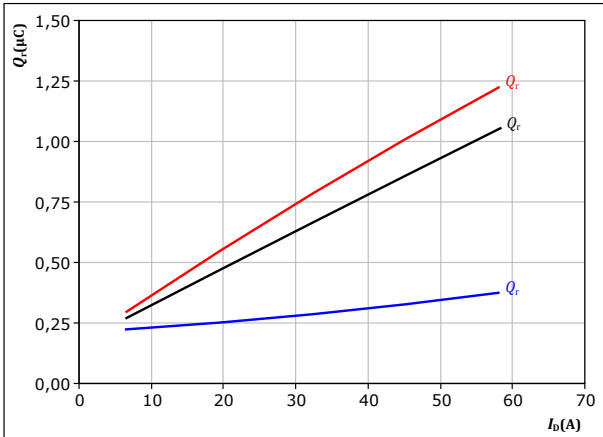


Inverter Switching Characteristics

figure 16. MOSFET

Typical recovered charge as a function of drain current

$$Q_r = f(I_D)$$

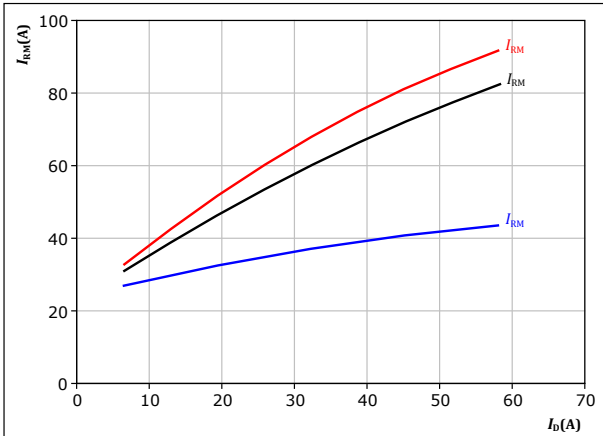


At $V_{DS} = 600$ V
 $V_{GS} = -5/18$ V
 $R_{gon} = 4$ Ω
 T_j : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 18. MOSFET

Typical peak reverse recovery current as a function of drain current

$$I_{RM} = f(I_D)$$

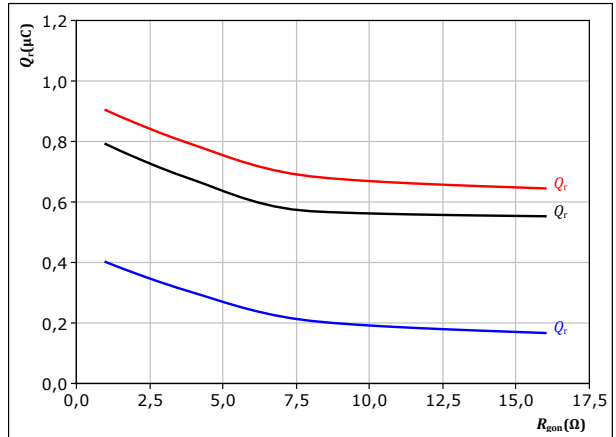


At $V_{DS} = 600$ V
 $V_{GS} = -5/18$ V
 $R_{gon} = 4$ Ω
 T_j : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 17. MOSFET

Typical recovered charge as a function of MOSFET turn on gate resistor

$$Q_r = f(R_{gon})$$

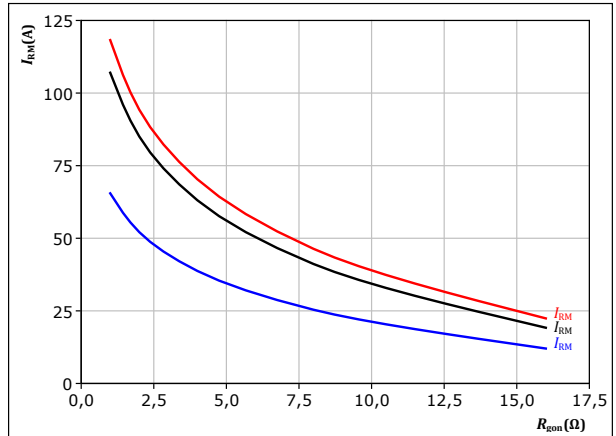


At $V_{DS} = 600$ V
 $V_{GS} = -5/18$ V
 $I_D = 32$ A
 T_j : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 19. MOSFET

Typical peak reverse recovery current as a function of MOSFET turn on gate resistor

$$I_{RM} = f(R_{gon})$$



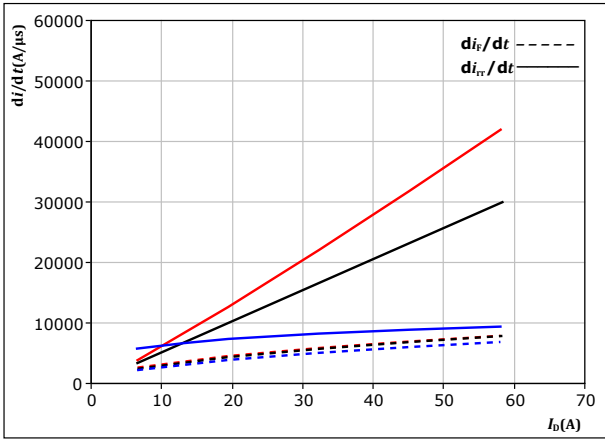
At $V_{DS} = 600$ V
 $V_{GS} = -5/18$ V
 $I_D = 32$ A
 T_j : 25 °C (blue), 125 °C (black), 150 °C (red)



Inverter Switching Characteristics

figure 20. MOSFET

Typical rate of fall of forward and reverse recovery current as a function of drain current
 $di_f/dt, di_{rr}/dt = f(I_D)$

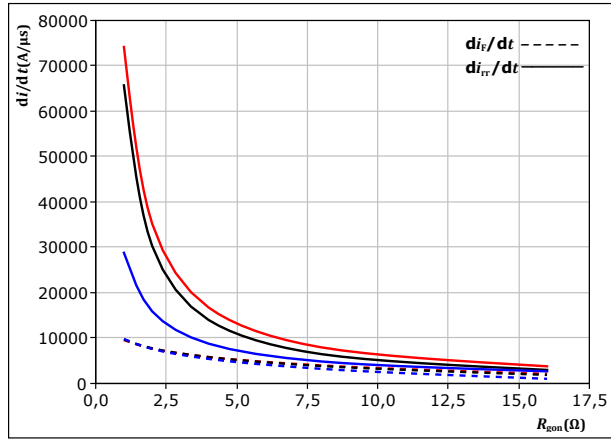


At $V_{DS} = 600$ V
 $V_{GS} = -5/18$ V
 $R_{g\text{on}} = 4$ Ω

$T_j = 25$ °C
 125 °C
 150 °C

figure 21. MOSFET

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_{rr}/dt = f(R_{g\text{on}})$

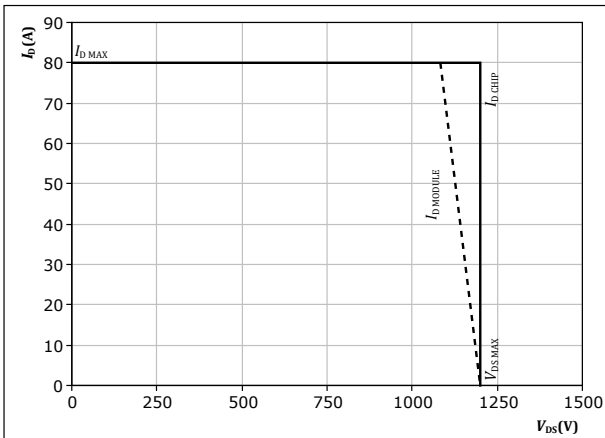


At $V_{DS} = 600$ V
 $V_{GS} = -5/18$ V
 $I_D = 32$ A

$T_j = 25$ °C
 125 °C
 150 °C

figure 22. MOSFET

Reverse bias safe operating area
 $I_D = f(V_{DS})$



At $T_j = 150$ °C
 $R_{g\text{on}} = 4$ Ω
 $R_{g\text{off}} = 4$ Ω



Inverter Switching Definitions

figure 23. MOSFET

Turn-off Switching Waveforms & definition of t_{doff} t_{Eoff} (t_{Eoff} = integrating time for E_{off})

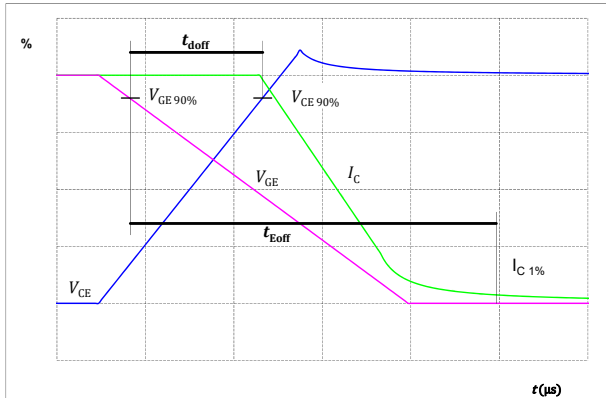


figure 24. MOSFET

Turn-on Switching Waveforms & definition of t_{don} t_{Eon} (t_{Eon} = integrating time for E_{on})

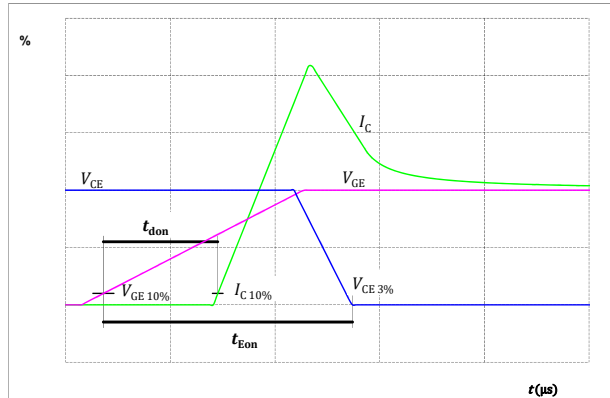


figure 25. MOSFET

Turn-off Switching Waveforms & definition of t_f

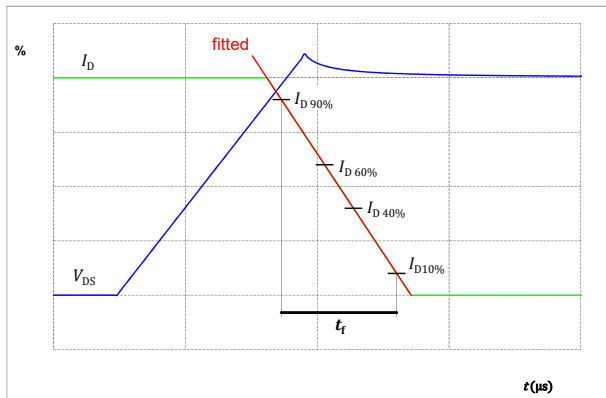
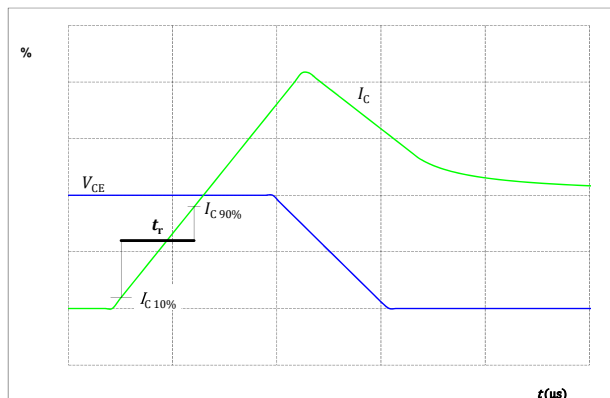


figure 26. MOSFET

Turn-on Switching Waveforms & definition of t_r





Inverter Switching Definitions

figure 27. FWD

Turn-off Switching Waveforms & definition of t_{tr}

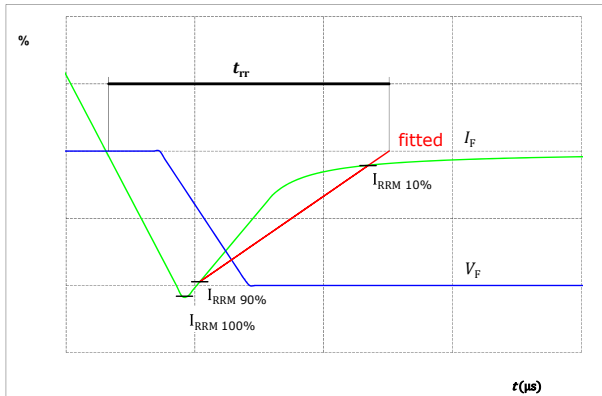


figure 28. FWD

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)

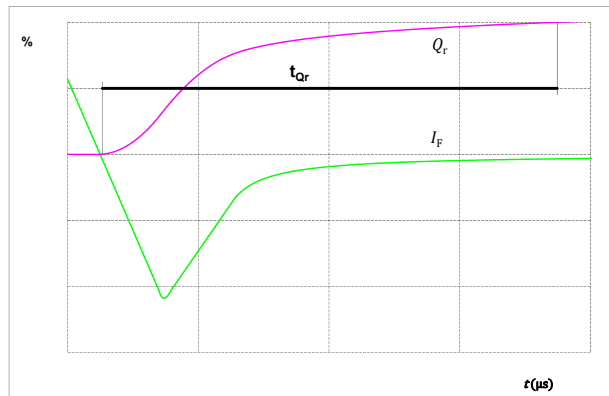
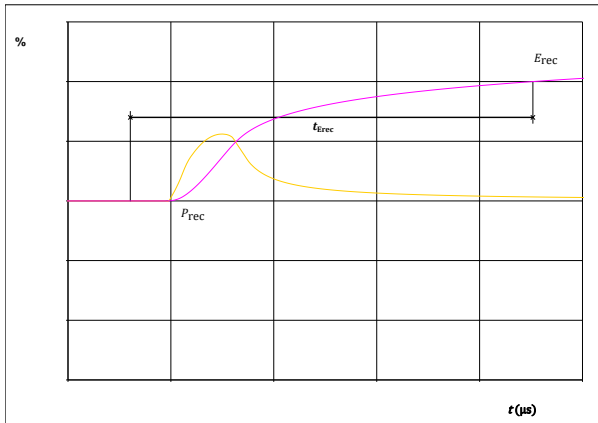


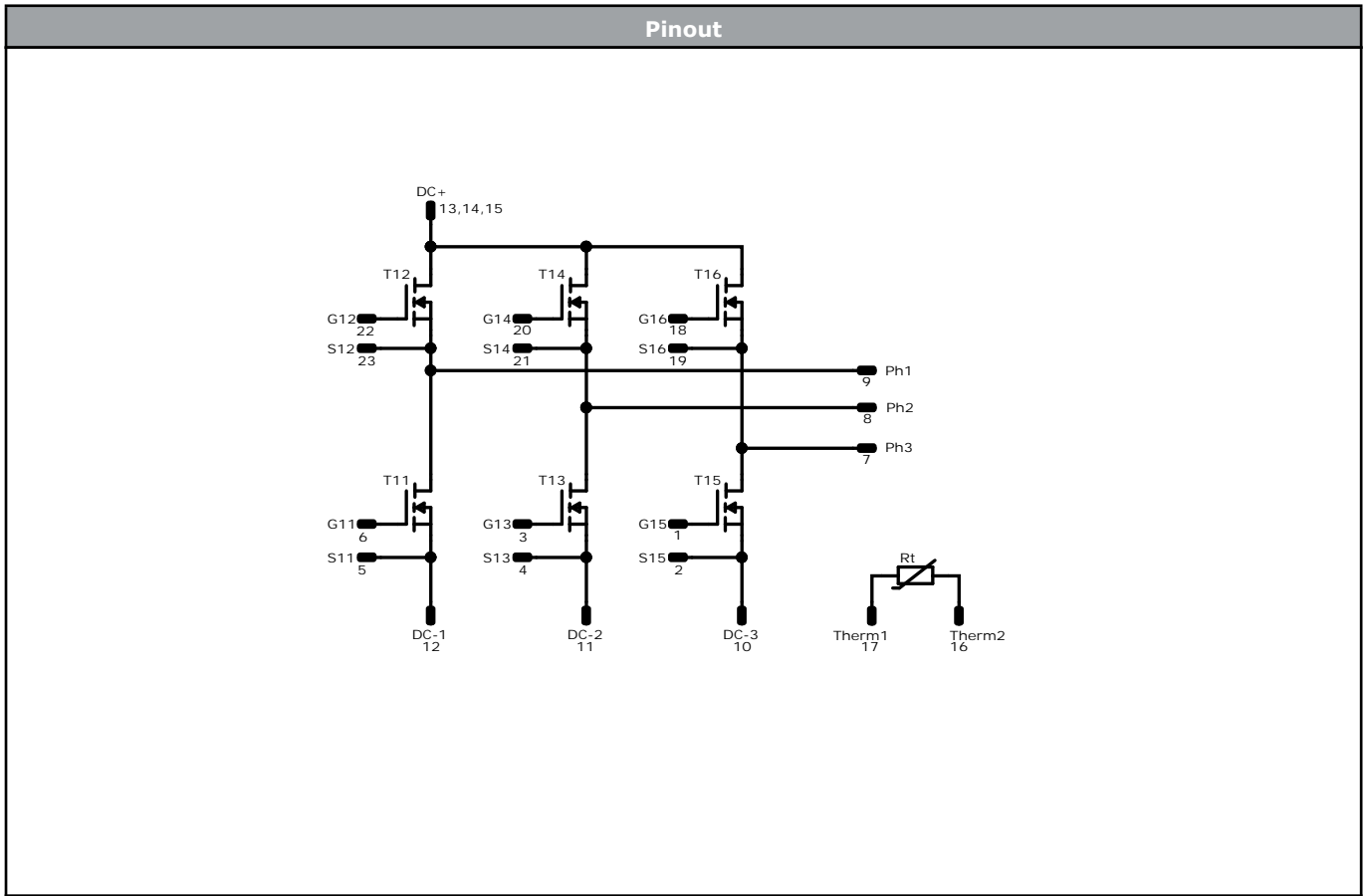
figure 29. FWD

Turn-on Switching Waveforms & definition of t_{Erec} (t_{Erec} = integrating time for E_{rec})





Vincotech



| Identification | | | | | |
|------------------------------|------------|---------|---------|-----------------|---------|
| ID | Component | Voltage | Current | Function | Comment |
| T11, T12, T13, T14, T15, T16 | MOSFET | 1200 V | 30 mΩ | Inverter Switch | |
| Rt | Thermistor | | | Thermistor | |



| Packaging instruction | | | | |
|---------------------------------------|------|----------|------|--------|
| Standard packaging quantity (SPQ) 100 | >SPQ | Standard | <SPQ | Sample |

| Handling instruction |
|--|
| Handling instructions for <i>flow</i> E1 packages see vincotech.com website. |

| Package data |
|---|
| Package data for <i>flow</i> E1 packages see vincotech.com website. |

| Vincotech thermistor reference |
|--|
| See Vincotech thermistor reference table at vincotech.com website. |

| UL recognition and file number |
|--|
| This device is UL 1557 recognized under E192116 up to a junction temperature under switching condition $T_{j,op}=175^{\circ}C$ and up to 3500VAC/1min isolation voltage. For more information see vincotech.com website. |



| Document No.: | Date: | Modification: | Pages |
|--------------------------------|--------------|-----------------|-------|
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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.